



# BIPOLAR ANALOG INTEGRATED CIRCUIT

# $\mu$ PC8233TK

## SiGe:C LOW NOISE AMPLIFIER FOR GPS/MOBILE COMMUNICATIONS

### DESCRIPTION

The  $\mu$ PC8233TK is a silicon germanium carbon (SiGe:C) monolithic integrated circuit designed as low noise amplifier for GPS and mobile communications. This device exhibits low noise figure and high power gain characteristics. This device is suitable for the reduction in power consumption of the mobile communication system because it operates by low voltage and low current.

The package is 6-pin lead-less minimold, suitable for surface mount.

This IC is manufactured using our UHS4 (Ultra High Speed Process) SiGe:C bipolar process.

### FEATURES

- Supply voltage :  $V_{CC} = 1.7$  to  $3.3$  V (2.7 V TYP.)
- Low noise : NF = 0.90 dB TYP. @  $V_{CC} = 2.7$  V,  $f_{in} = 1575$  MHz  
NF = 0.90 dB TYP. @  $V_{CC} = 1.8$  V,  $f_{in} = 1575$  MHz
- High gain : GP = 20 dB TYP. @  $V_{CC} = 2.7$  V,  $f_{in} = 1575$  MHz  
GP = 19.5 dB TYP. @  $V_{CC} = 1.8$  V,  $f_{in} = 1575$  MHz
- Low current consumption :  $I_{CC} = 3.5$  mA TYP. @  $V_{CC} = 2.7$  V
- Built-in power-saving function  $V_{Pson} = 1.0$ V to  $V_{CC}$   $V_{Psoff} = 0.0$  to  $0.4$ V
- High-density surface mounting : 6-pin lead-less minimold package ( $1.5 \times 1.1 \times 0.55$  mm)
- Included very robust bandgap regulator (Small  $V_{CC}$  and  $T_A$  dependence)
- Included protection circuits for ESD

### APPLICATION

- Low noise amplifier for GPS and mobile communications

### ORDERING INFORMATION

| Part Number       | Order Number        | Package  | Marking | Supplying Form   |
|-------------------|---------------------|--|---------|--|
| $\mu$ PC8233TK-E2 | $\mu$ PC8233TK-E2-A | 6-pin lead-less minimold<br>(1511 PKG) (Pb-Free) | TBD     | <ul style="list-style-type: none"> <li>• 8 mm wide embossed taping</li> <li>• Pin 1, 6 face the perforation side of the tape</li> <li>• Qty 5 kpcs/reel</li> </ul> |

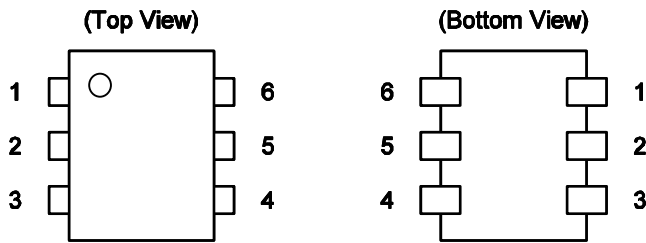
**Remark** To order evaluation samples, contact your nearby sales office.

Part number for sample order:  $\mu$ PC8233TK

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

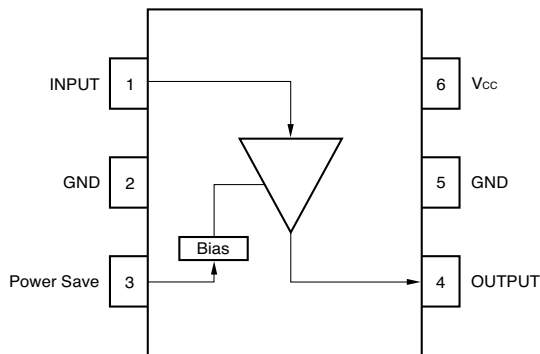
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**PIN CONNECTIONS**



| Pin No. | Pin Name        |
|---------|-----------------|
| 1       | INPUT           |
| 2       | GND             |
| 3       | Power Save      |
| 4       | OUTPUT          |
| 5       | GND             |
| 6       | V <sub>CC</sub> |

**INTERNAL BLOCK DIAGRAM**



**ABSOLUTE MAXIMUM RATINGS**

| Parameter                     | Symbol           | Test Conditions                    | Ratings     | Unit |
|-------------------------------|------------------|------------------------------------|-------------|------|
| Supply Voltage                | V <sub>CC</sub>  | T <sub>A</sub> = +25°C             | 4.0         | V    |
| Power-Saving Voltage          | V <sub>PS</sub>  | T <sub>A</sub> = +25°C             | 4.0         | V    |
| Power Dissipation             | P <sub>D</sub>   | T <sub>A</sub> = +85°C <b>Note</b> | 232         | mW   |
| Operating Ambient Temperature | T <sub>A</sub>   |                                    | -40 to +85  | °C   |
| Storage Temperature           | T <sub>stg</sub> |                                    | -55 to +150 | °C   |
| Input Power                   | P <sub>in</sub>  |                                    | +10         | dBm  |

**Note** Mounted on double-side copper-clad 50 × 50 × 1.6 mm epoxy glass PWB

**RECOMMENDED OPERATING RANGE**

| Parameter                     | Symbol             | MIN. | TYP. | MAX.            | Unit |
|-------------------------------|--------------------|------|------|-----------------|------|
| Supply Voltage                | V <sub>CC</sub>    | 1.7  | 2.7  | 3.3             | V    |
| Operating Ambient Temperature | T <sub>A</sub>     | -40  | +25  | +85             | °C   |
| Power Save Turn-on Voltage    | V <sub>PSon</sub>  | 1.0  | -    | V <sub>CC</sub> | V    |
| Power Save Turn-off Voltage   | V <sub>PSoff</sub> | 0    | -    | 0.4             | V    |

**ELECTRICAL CHARACTERISTICS**

( $T_A = +25^\circ\text{C}$ ,  $V_{CC} = V_{PS} = 2.7\text{ V}$ ,  $f_{in} = 1575\text{ MHz}$ , unless otherwise specified)

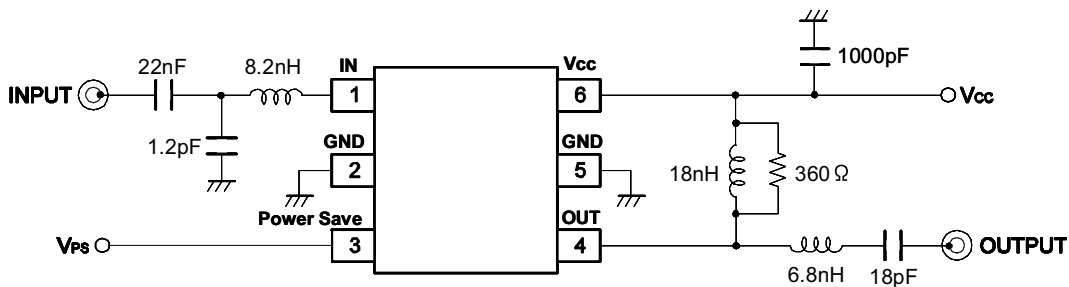
| Parameter                                  | Symbol                 | Test Conditions  | MIN. | TYP. | MAX. | Unit |
|--|------------------------|--|------|------|------|------|
| Circuit Current                            | I <sub>CC</sub>        | No Signal ( $V_{PS} = 2.7\text{ V}$ )                    | 2.5  | 3.5  | 4.8  | mA   |
|  |                        | At Power-Saving Mode ( $V_{PS} = 0\text{ V}$ )           | –    | –    | 1    | μA   |
| Power Gain                                 | G <sub>P</sub>         | P <sub>in</sub> = –35 dBm                                | 17.5 | 20   | 22.5 | dB   |
| Noise Figure                               | NF                     |  | –    | 0.9  | 1.2  | dB   |
| Input 3rd Order Distortion Intercept Point | IIP <sub>3</sub>       | f <sub>in1</sub> = 1574 MHz, f <sub>in2</sub> = 1575 MHz | –    | –7.5 | –    | dBm  |
| Input Return Loss                          | RL <sub>in</sub>       |  | 7    | 16   | –    | dB   |
| Output Return Loss                         | RL <sub>out</sub>      |  | 8    | 16   | –    | dB   |
| Isolation                                  | ISL                    |  | –    | 36   | –    | dB   |
| Gain 1 dB Compression Input Power          | P <sub>in</sub> (1 dB) |  | –    | –23  | –    | dBm  |

**STANDARD CHARACTERISTICS FOR REFERENCE**

( $T_A = +25^\circ\text{C}$ ,  $V_{CC} = V_{PS} = 1.8\text{ V}$ ,  $f_{in} = 1575\text{ MHz}$ , unless otherwise specified)

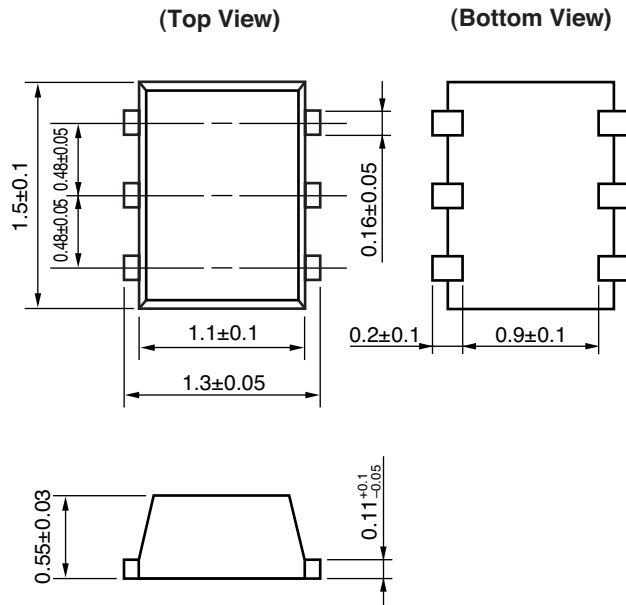
| Parameter                                  | Symbol                 | Test Conditions  | Reference | Unit |
|--|------------------------|--|-----------|------|
| Circuit Current                            | I <sub>CC</sub>        | No Signal ( $V_{PS} = 1.8\text{ V}$ )                    | 3.3       | mA   |
|  |                        | At Power-Saving Mode ( $V_{PS} = 0\text{ V}$ )           | –         | μA   |
| Power Gain                                 | G <sub>P</sub>         | P <sub>in</sub> = –35 dBm                                | 19.5      | dB   |
| Noise Figure                               | NF                     |  | 0.9       | dB   |
| Input 3rd Order Distortion Intercept Point | IIP <sub>3</sub>       | f <sub>in1</sub> = 1574 MHz, f <sub>in2</sub> = 1575 MHz | –8        | dBm  |
| Input Return Loss                          | RL <sub>in</sub>       |  | 16        | dB   |
| Output Return Loss                         | RL <sub>out</sub>      |  | 15.5      | dB   |
| Isolation                                  | ISL                    |  | 36        | dB   |
| Gain 1 dB Compression Input Power          | P <sub>in</sub> (1 dB) |  | –23.5     | dBm  |

**TEST CIRCUIT**



**PACKAGE DIMENSIONS**

**6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)**



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**NOTES ON CORRECT USE**

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation). All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.

**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

| Soldering Method | Soldering Conditions  | Condition Symbol |
|------------------|---|------------------|
| Infrared Reflow  | Peak temperature (package surface temperature) : 260°C or below<br>Time at peak temperature : 10 seconds or less<br>Time at temperature of 220°C or higher : 60 seconds or less<br>Preheating time at 120 to 180°C : 120±30 seconds<br>Maximum number of reflow processes : 3 times<br>Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below | IR260            |
| Wave Soldering   | Peak temperature (molten solder temperature) : 260°C or below<br>Time at peak temperature : 10 seconds or less<br>Preheating temperature (package surface temperature) : 120°C or below<br>Maximum number of flow processes : 1 time<br>Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below  | WS260            |
| Partial Heating  | Peak temperature (terminal temperature) : 350°C or below<br>Soldering time (per side of device) : 3 seconds or less<br>Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below   | HS350            |

**Caution Do not use different soldering methods together (except for partial heating).**

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M8E 02. 11-1

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CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL’s understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

| Restricted Substance per RoHS | Concentration Limit per RoHS (values are not yet fixed) | Concentration contained in CEL devices |     |
|-------------------------------|---|--|-----|
|                               |   | -A                                     | -AZ |
| Lead (Pb)                     | < 1000 PPM  | Not Detected                           | (*) |
| Mercury                       | < 1000 PPM  | Not Detected                           |     |
| Cadmium                       | < 100 PPM   | Not Detected                           |     |
| Hexavalent Chromium           | < 1000 PPM  | Not Detected                           |     |
| PBB                           | < 1000 PPM  | Not Detected                           |     |
| PBDE                          | < 1000 PPM  | Not Detected                           |     |

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